

# 1.5V Drive Nch MOSFET

# **RT1C060UN**

#### Structure

Silicon N-channel MOSFET

#### ● Features

- 1) Low on-resistance.
- 2) High power package (TSST8).
- 3) Low voltage drive (1.5V drive).

### Application

Switching

#### Packaging specifications

	• 1		
	Package	Taping	
Type	Code	TR	
	Basic ordering unit (pieces)	3000	
RT1C060U	0		

### ● Absolute maximum ratings (Ta = 25°C)

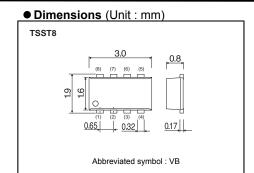
Parameter		Symbol	Limits	Unit
Drain-source voltage		$V_{DSS}$	20	V
Gate-source voltage		$V_{GSS}$	±10	V
Drain current	Continuous	$I_D$	±6	Α
	Pulsed	I <sub>DP</sub> *1	±24	Α
Source current (Body Diode)	Continuous	I <sub>S</sub>	1	Α
	Pulsed	I <sub>SP</sub> *1	24	Α
Power dissipation		P <sub>D</sub> *2	1.25	W
Channel temperature		Tch	Tch 150	
Range of storage temperature		Tstg	-55 to +150	°C

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1%

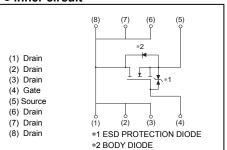
#### • Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to Ambient	Rth (ch-a)*	100	°C/W

<sup>\*</sup> Each terminal mounted on a ceramic board.



#### Inner circuit



<sup>\*2</sup> Each terminal mounted on a ceramic board.

## ● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	1	-	±10	μA	$V_{GS}$ =±10V, $V_{DS}$ =0V
Drain-source breakdown voltage	$V_{(BR)DSS}$	20	-	-	٧	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	1	μA	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	0.3	-	1.0	٧	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA
		1	20	28		I <sub>D</sub> =6A, V <sub>GS</sub> =4.5V
Static drain-source on-state	R *	1	24	33	m()	I <sub>D</sub> =6A, V <sub>GS</sub> =2.5V
resistance	R <sub>DS (on)</sub>	-	28	39	mΩ	I <sub>D</sub> =3A, V <sub>GS</sub> =1.8V
		1	33	66		I <sub>D</sub> =1.2A, V <sub>GS</sub> =1.5V
Forward transfer admittance	I Y <sub>fs</sub> f*	5.5	-	-	S	I <sub>D</sub> =6A, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	1	870	-	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	1	190	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	1	85	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	1	7	-	ns	I <sub>D</sub> =3A, V <sub>DD</sub> ≒ 10V
Rise time	t <sub>r</sub> *	ı	30	-	ns	V <sub>GS</sub> =4.5V
Turn-off delay time	t <sub>d(off)</sub> *	-	75	-	ns	$R_L$ =3.3 $\Omega$
Fall time	t <sub>f</sub> *	-	20	-	ns	$R_G$ =10 $\Omega$
Total gate charge	Q <sub>g</sub> *	-	11	_	nC	I <sub>D</sub> =6A, V <sub>DD</sub> ≒10V
Gate-source charge	Q <sub>gs</sub> *	-	2.0	-	nC	$V_{GS}$ =4.5V R <sub>L</sub> =1.7 $\Omega$
Gate-drain charge	Q <sub>gd</sub> *	-	2.1	-	nC	$R_G$ =10 $\Omega$

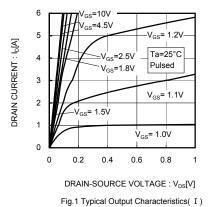
<sup>\*</sup>Pulsed

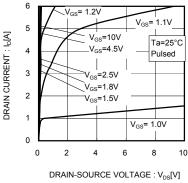
# ●Body diode characteristics (Source-Drain) (Ta = 25°C)

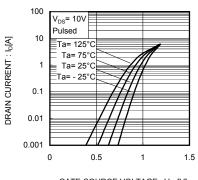
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	V <sub>SD</sub> *	-	-	1.2	V	I <sub>s</sub> =6A, V <sub>GS</sub> =0V

<sup>\*</sup>Pulsed

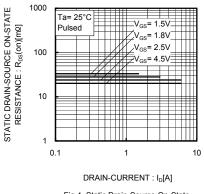
#### Electrical characteristic curves

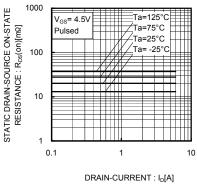






GATE-SOURCE VOLTAGE :  $V_{GS}[V]$ Fig.2 Typical Output Characteristics( II) Fig.3 Typical Transfer Characteristics





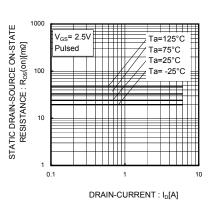
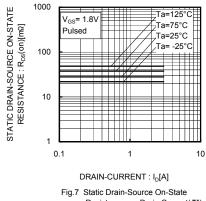
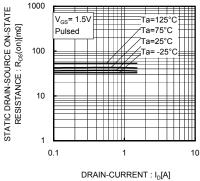


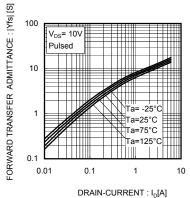
Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II)

Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III)



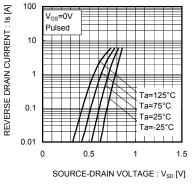


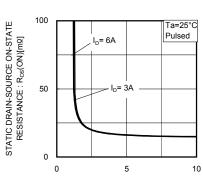


Resistance vs. Drain Current( IV)

Fig.8 Static Drain-Source On-State Resistance vs. Drain Current( V)

Fig.9 Forward Transfer Admittance vs. Drain Current





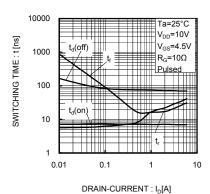
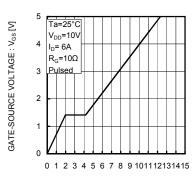


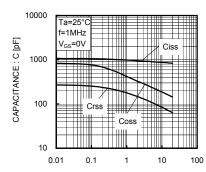
Fig.10 Reverse Drain Current vs. Sourse-Drain Voltage

GATE-SOURCE VOLTAGE : V<sub>GS</sub>[V]

Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

Fig.12 Switching Characteristics





TOTAL GATE CHARGE : Qg [nC]

Fig.13 Dynamic Input Characteristics

DRAIN-SOURCE VOLTAGE :  $V_{DS}[V]$ Fig.14 Typical Capacitance vs. Drain-Source Voltage

### Measurement circuits

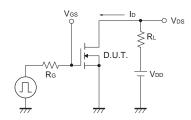


Fig.1-1 Switching time measurement circuit

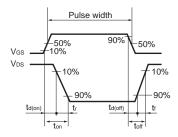


Fig.1-2 Switching waveforms

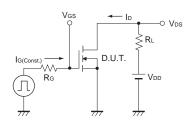


Fig.2-1 Gate charge measurement circuit

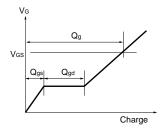


Fig.2-2 Gate Charge Waveform

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